



SLOVENSKI STANDARD
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Vmesniki univerzalnega serijskega vodila za prenos podatkov in napajanje - 1-2.
del: Skupne komponente - Specifikacija za zagotavljanje napajanja prek USB

Universal serial bus interfaces for data and power - Part 1-2: Common components -
USB Power Delivery specification

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ICS:

35.200	Vmesniška in povezovalna oprema	Interface and interconnection equipment
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100/3189/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

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DATE OF CIRCULATION: 2019-01-25	CLOSING DATE FOR VOTING: 2019-04-19
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IEC TA 18 : MULTIMEDIA HOME SYSTEMS AND APPLICATIONS FOR END-USER NETWORKS	
SECRETARIAT: Japan	SECRETARY: Mr Keisuke Koide
OF INTEREST TO THE FOLLOWING COMMITTEES:	PROPOSED HORIZONTAL STANDARD: <input type="checkbox"/> Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.
FUNCTIONS CONCERNED: <input type="checkbox"/> EMC <input type="checkbox"/> ENVIRONMENT <input type="checkbox"/> QUALITY ASSURANCE <input type="checkbox"/> SAFETY	
<input checked="" type="checkbox"/> SUBMITTED FOR CENELEC PARALLEL VOTING Attention IEC-CENELEC parallel voting The attention of IEC National Committees, members of CENELEC, is drawn to the fact that this Committee Draft for Vote (CDV) is submitted for parallel voting. The CENELEC members are invited to vote through the CENELEC online voting system.	<input type="checkbox"/> NOT SUBMITTED FOR CENELEC PARALLEL VOTING

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TITLE:

Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification

PROPOSED STABILITY DATE: 2023

NOTE FROM TC/SC OFFICERS:

INTERNATIONAL ELECTROTECHNICAL COMMISSION

UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER

Part 1-2: Common components – USB Power Delivery specification

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FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

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- 58 • reconfirmed,
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70 Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of
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72 This standard is the USB-IF publication Universal Serial Bus Power Delivery Specification Revision
73 3.0, Version 1.2.

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Universal Serial Bus Power Delivery Specification

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Revision History

Revision	Version	Comments	Issue Date
1.0	1.0	Initial release Revision 1.0	5 July, 2012
1.0	1.1	Including errata through 31-October-2012	31 October 2012
1.0	1.2	Including errata through 26-June-2013	26 June, 2013
1.0	1.3	Including errata through 11-March-2014	11 March 2014
2.0	1.0	Initial release Revision 2.0	11 August 2014
2.0	1.1	Including errata through 7-May 2015	7 May 2015
2.0	1.2	Including errata through 25-March-2016	25 March 2016
2.0	1.3	Including errata through 11-January-2017	11 January 2017
3.0	1.0	Initial release Revision 3.0	11 December 2015
3.0	1.0a	Including errata through 25-March-2016	25 March 2016
3.0	1.1	Including errata through 12-January-2016	12 January 2017
3.0	1.2	Including errata through 21-June-2018:	21 June 2018

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